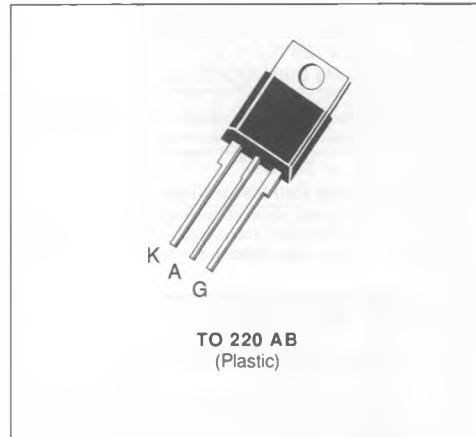


THYRISTORS

- GLASS PASSIVATED CHIP
- POSSIBILITY OF MOUNTING ON PRINTED CIRCUIT
- AVAILABLE IN NON-INSULATED VERSION → TYN SERIES OR IN INSULATED VERSION → TXN SERIES (INSULATING VOLTAGE 2500 VRMS)
- UL RECOGNIZED FOR TXN SERIES (E81734)



DESCRIPTION

SCR's designed for motor control, heating controls, power supplies...

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value		Unit
$I_{T(RMS)}$	RMS on-state Current (1)	$T_c = 75^\circ\text{C}$	10	A
$I_{T(AV)}$	Mean on-state Current (1)	$T_c = 75^\circ\text{C}$	6.4	A
I_{TSM}	Non Repetitive Surge Peak on-state Current (T_j initial = 25 °C) (2)	$t = 8.3 \text{ ms}$	105	A
		$t = 10 \text{ ms}$	100	
I^2t	I^2t Value for Fusing	$t = 10 \text{ ms}$	50	A^2s
dI/dt	Critical Rate of Rise of on-state Current (3)		50	$\text{A}/\mu\text{s}$
T_{STG} T_j	Storage and Operating Junction Temperature Range		-40 to 110 -40 to 110	$^\circ\text{C}$ $^\circ\text{C}$

Symbol	Parameter	TXN/TYN							Unit
		0510	110	210	410	610	810	1010	
V_{DRM} V_{RRM}	Repetitive Peak off-state Voltage (4)	50	100	200	400	600	800	1000	V

(1) Single phase circuit, 180° conduction angle.

(2) Half sine wave.

(3) $I_G = 150 \text{ mA}$ $dI/dt = 1 \text{ A}/\mu\text{s}$.

(4) $T_j = 110 \text{ }^\circ\text{C}$.

THERMAL RESISTANCES

Symbol	Parameter	Value		Unit
$R_{th(j-c)}$	Junction-case for D.C.	3.8		$^\circ\text{C}/\text{W}$
$R_{th(j-a)}$	Junction-ambient	60		$^\circ\text{C}/\text{W}$

GATE CHARACTERISTICS (maximum values)

$$P_{GM} = 20 \text{ W } (t_D = 20 \mu\text{s})$$

$$I_{FGM} = 2 \text{ A} \quad (t_0 = 20 \text{ } \mu\text{s})$$

$$V_{RGM} = 5 \text{ V}$$

$$P_G(\text{AV}) = 0.5 \text{ W}$$

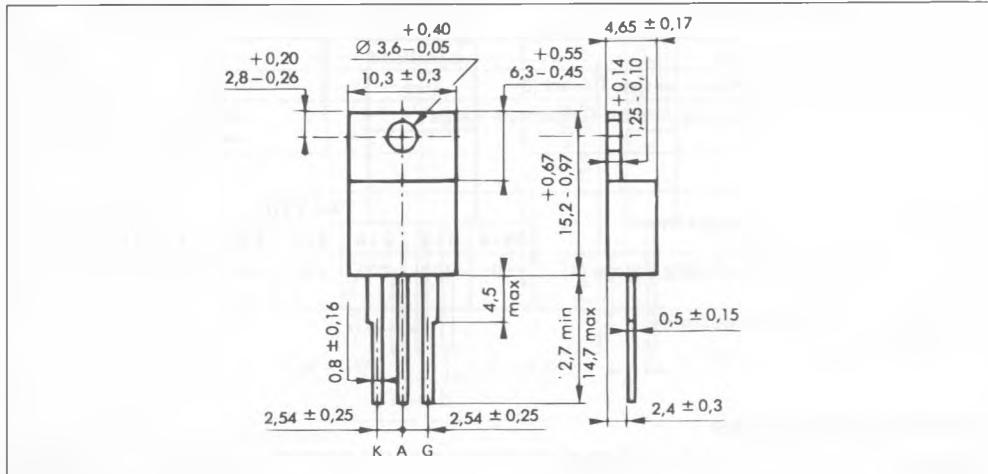
$$V_{FGM} = 15 \text{ V } (t_0 = 20 \mu\text{s})$$

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
I _{GT}	T _j = 25 °C Pulse Duration > 20 µs	V _D = 12 V	R _L = 33 Ω			15	mA
V _{GT}	T _j = 25 °C Pulse Duration > 20 µs	V _D = 12 V	R _L = 33 Ω			1.5	V
V _{GD}	T _j = 110 °C	V _D = V _{DRM}	R _L = 3.3 kΩ	0.2			V
I _H	T _j = 25 °C	I _T = 100 mA	Gate Open			30	mA
I _L	T _j = 25 °C Pulse Duration > 20 µs	V _D = 12 V	I _G = 30 mA		50		mA
V _{TM}	T _j = 25 °C	I _{TM} = 20 A	t _p = 10 ms			1.6	V
I _{DRM}	V _{DRM} Specified		T _j = 25 °C			0.01	mA
			T _j = 110 °C			1	
I _{RRM}	V _{RRM} Specified		T _j = 25 °C			0.01	mA
			T _j = 110 °C			1	
t _{gt}	T _j = 25 °C I _G = 40 mA	V _D = V _{DRM} di _D /dt = 0.45 A/µs	I _T = 20 A		2		µs
t _q	T _j = 110 °C V _D = 67 % V _{DRM} Gate Open	I _T = 20 A di/dt = 30 A/µs	V _R = 25 V dv/dt = 50 V/µs		70		µs
dv/dt*	T _j = 110 °C Linear Slope up to V _D = 67 % V _{DRM}	Gate Open		200			V/µs

* For higher guaranteed values, please consult us.

PACKAGE MECHANICAL DATA : TO 220 AB Plastic



Cooling method : by conduction (method C)

Cooling method : by air
Marking : type number

Weight: 2 g

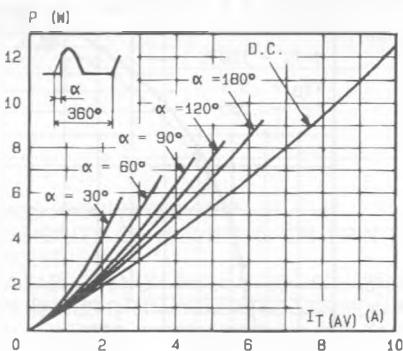


Fig.1 - Maximum mean power dissipation versus mean on-state current.

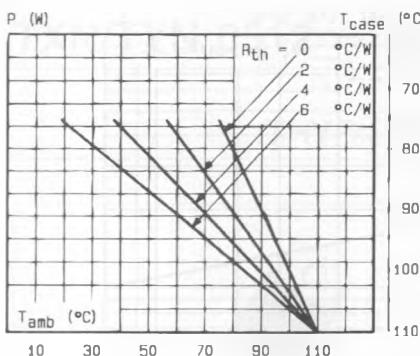


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

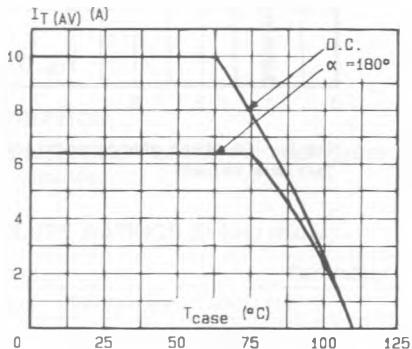


Fig.3 - Mean on-state current versus case temperature.

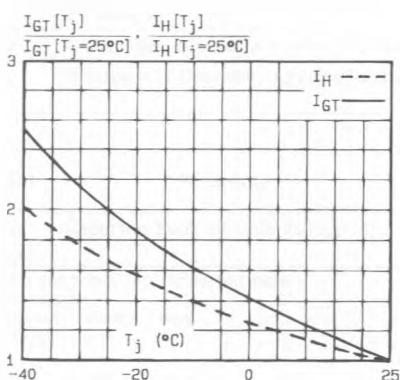


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

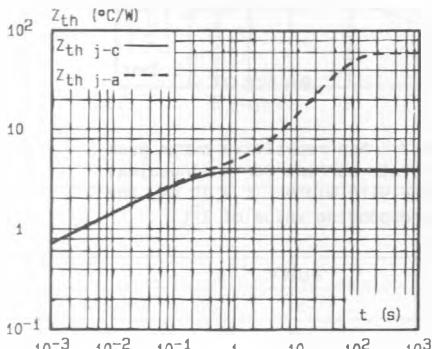


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

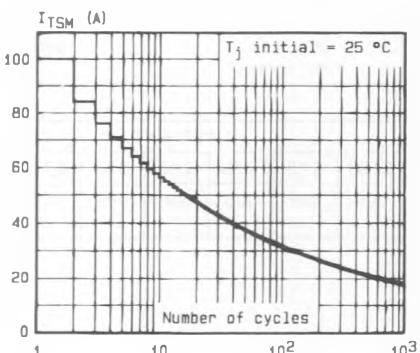


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

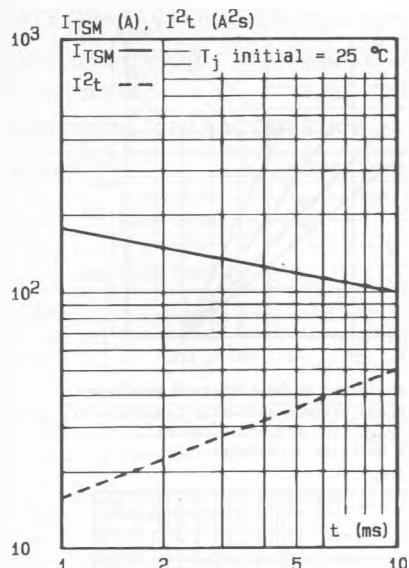


Fig.7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

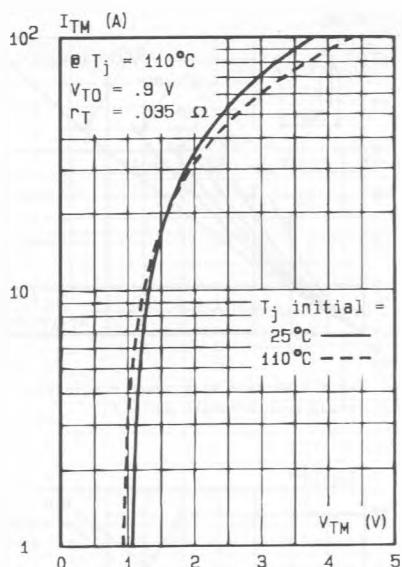


Fig.8 - On-state characteristics (maximum values).